

General Description

The GL4606-D8 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications. The package form is SOP-8, which accords with the RoHS standard.

Features

- N-Channel

- $V_{DS} = 30V, I_D = 8A$
- $R_{DS(ON)} < 20m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} < 30m\Omega @ V_{GS}=4.5V$
- $R_{DS(ON)} < 40m\Omega @ V_{GS}=2.5V$

- P-Channel

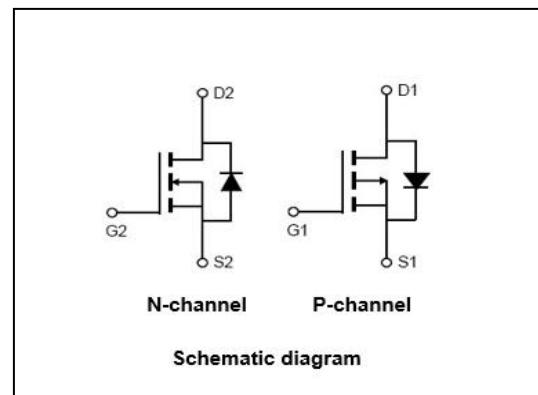
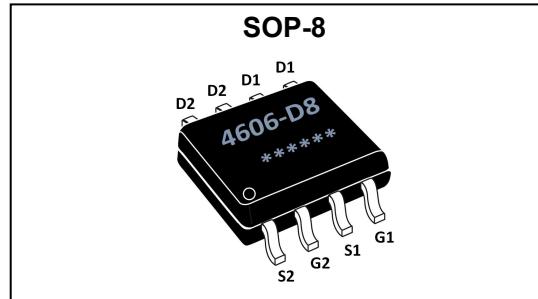
- $V_{DS} = -30V, I_D = -8.0A$
- $R_{DS(ON)} < 30m\Omega @ V_{GS}=-10V$
- $R_{DS(ON)} < 50m\Omega @ V_{GS}=-4.5V$
- $R_{DS(ON)} < 65m\Omega @ V_{GS}=-2.5V$

- Low On-Resistance

- Low Input Capacitance

- Fast Switching Speed

- Low Input/Output Leakage



Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage		V_{DS}	30	-30	V
Gate-Source Voltage		V_{GS}	± 12	± 12	V
Continuous Drain Current	$T_A=25^\circ C$	I_D	8	-8	A
	$T_A=70^\circ C$		7.2	-7.2	
Pulsed Drain Current ^(Note 1)		I_{DM}	32	-32	A
Maximum Power Dissipation	$T_A=25^\circ C$	P_D	2.0	2.0	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 To 150	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	N-Ch	62.5	°C/W
Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	P-Ch	62.5	°C/W



GL4606-D8

GL Silicon N+P Channel Power MOSFET

N-CH Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	30	33	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=30\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$\text{V}_{\text{GS}}=\pm 12\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	± 1	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	0.6	1.0	2.5	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=6\text{A}$	-	14	20	$\text{m}\Omega$
Drain-Source On-State Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=5\text{A}$	-	21	30	$\text{m}\Omega$
Drain-Source On-State Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=2.5\text{V}, \text{I}_D=4\text{A}$	-	30	40	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=8\text{A}$	15	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $\text{F}=1.0\text{MHz}$	-	320	-	PF
Output Capacitance	C_{oss}		-	54	-	PF
Reverse Transfer Capacitance	C_{rss}		-	41	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{DD}}=15\text{V}, \text{R}_L=2.5\Omega$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_{\text{GEN}}=3\Omega$	-	5.5	-	nS
Turn-on Rise Time	t_r		-	3.0	-	nS
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$		-	16.5	-	nS
Turn-Off Fall Time	t_f		-	4.5	-	nS
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=15\text{V}, \text{I}_D=8\text{A},$ $\text{V}_{\text{GS}}=10\text{V}$	-	15	-	nC
Gate-Source Charge	Q_{gs}		-	6.5	-	nC
Gate-Drain Charge	Q_{gd}		-	4.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=8\text{A}$	-	0.8	1.2	V



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P-CH Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-33	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	-1	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.6	-1.0	-2.5	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-6.0\text{ A}$	-	22	30	$\text{m}\Omega$
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5.0\text{A}$	-	30	50	$\text{m}\Omega$
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-4.0\text{A}$	-	45	60	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-8\text{A}$	10	-	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	630	-	PF
Output Capacitance	C_{oss}		-	110	-	PF
Reverse Transfer Capacitance	C_{rss}		-	76	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=-15\text{V}, R_{\text{L}}=2.3\Omega$ $V_{\text{GS}}=-10\text{V}, R_{\text{GEN}}=6\Omega$	-	8.5	-	nS
Turn-on Rise Time	t_r		-	6.5	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	21	-	nS
Turn-Off Fall Time	t_f		-	8.5	-	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-8\text{A}$ $V_{\text{GS}}=-10\text{V}$	-	10.2	-	nC
Gate-Source Charge	Q_{gs}		-	1.9	-	nC
Gate-Drain Charge	Q_{gd}		-	2.4	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-8\text{A}$	-	-	-1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production